PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Christos J. Georgiou, et al. **Docket:** FIS920030113US1 (16497)

Serial No.: 10/604,491 **Dated:** August 11,.2003

Filed: 07/25/03

For: SELF-CONTAINED PROCESSOR SUBSYSTEM
AS COMPONENT FOR SYSTEM-ON-CHIP DESIGN

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

Pursuant to 37 C.F.R. §§1.56, 1.97 and 1.98, applicants submit the following references which applicants believe may be material to the above-identified patent application. A copy of the references which applicants wish to make of record in this case is enclosed herein for the Examiner=s convenience along with a listing on Form PTO-1449 attached.

1. Motorola intelligence everywhere™ digital dna™*, Fact Sheet MPC8560 POWERQUICC™ INTEGRATED COMMUNICATIONS PROCESSOR, Motorola, Inc., 2002;

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, P.O. Box 1450, Alexandria, VA 22313-1450 on 8/11/03

Dated: 8/11/03

2. Nair, R., "Effect of increasing chip density on the evolution of computer architectures", IBM J. RES. & DEV., Vol. 46, No. 2/3, March/May 2002, pp. 223-234;

3. Ryu, et al., "A Comparison of Five Different Multi processor SoC Bus Architectures", Georgia Institute of Technology Electrical and Computer Engineering, Atlanta, GA;

4. Brinkman, et al., "On-Chip Interconnects for Next Generation System-on-Chips", Heinz Nixdorf Institute and Department of Electrical Engineering, University of Paderborn, Germany, Fraunhofer Institute of Microelectronic Circuits and Systems, Duisburg, Germany; and

5. Berry, "SYSTEM-ON-CHIP MARKETS AND TRENDS", Electronic Trend Publications, Inc. San Jose, CA, Second Edition, 2003, pp. 1-1 –5-2;

All the references listed on Form PTO-1449 are in the English language, thus, a concise explanation of those references required by 37 C.F.R. §1.98(a)(3) is not necessary.

Respectfully submitted,

8-11-03

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INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

Docket Number (Optional)	Application Number
FIS920030113US1 (16497)	10/604,491
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07/25/03	Unassigned

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation YES	Translation NO

OTHER DOCUMENTS *(Including Author, Title, Date, Pertinent Pages, Etc.)*

		Motorola intelligence everywhereTM digital dnaTM*, Fact Sheet MPC8560 POWERQUICCTM INTEGRATED COMMUNICATIONS PROCESSOR, Motorola, Inc., 2002
		Nair, R., "Effect of increasing chip density on the evolution of computer architectures", IBM J. RES. & DEV., Vol. 46, No. 2/3, March/May 2002, pp. 223-234

EXAMINER	DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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		Ryu, et al., "A Comparison f Five Different Multi processor SoC Bus Architectures", Georgia Institute of Technology Electrical and Computer Engineering, Atlanta, GA
		Brinkman, et al., "On-Chip Interconnects for Next Generation System-on-Chips", Heinz Nixdorf Institute and Department of Electrical Engineering, University of Paderborn, Germany, Fraunhofer Institute of Microelectronic Circuits and Systems, Duisburg, Germany
		Berry, "SYSTEM-ON-CHIP MARKETS AND TRENDS", Electronic Trend Publications, Inc. San Jose, CA, Second Edition, 2003, pp. 1-1 -5-2

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